

Manufacturer: Shenzhen Pipijia technology Co., LTD

Address: 1716 Shangyou Mansion, Yousong Village, Longhua Street, Longhua District, Shenzhen

SPECIFICATIONS

DESCRIPTION: Bluetooth antenna

CUSTOMER PART No:

OUR MODEL NO: **PBX3216MP01**

DATE: 2020/12/22

PLEASE RETURN TO US ONE COPY OF “SPECIFICATION FOR APPROVAL”
WITH YOUR APPROVED SIGNATURES

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DESIGNED BY: Sera	APPROVED BY: XD		
TITLE: CHIP2450-3216 Specification		DOCUMENT NO.	SPEC REV.
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PBX3216MP01 Specification

Operating Temp. : -40°C~+85°C

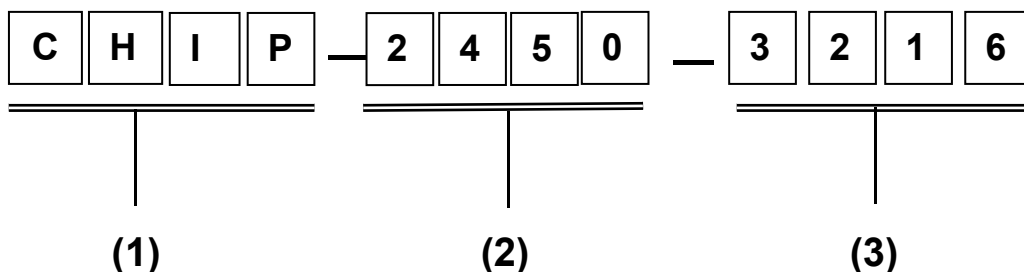
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

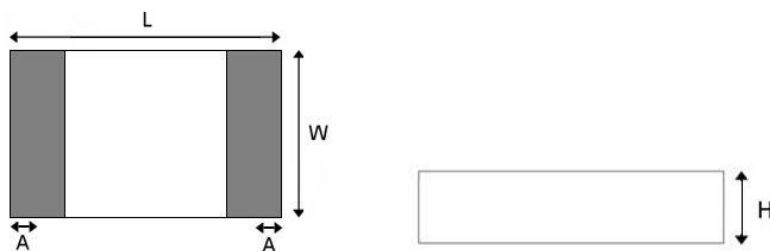
- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

3. PRODUCT IDENTIFICATION



- (1) Product type: Multilayer chip Antenna
(2) Center Frequency: 2450MHz
(3) External Dimensions (L×W) (mm): 3.2*1.6

4. SHAPE AND DIMENSIONS:

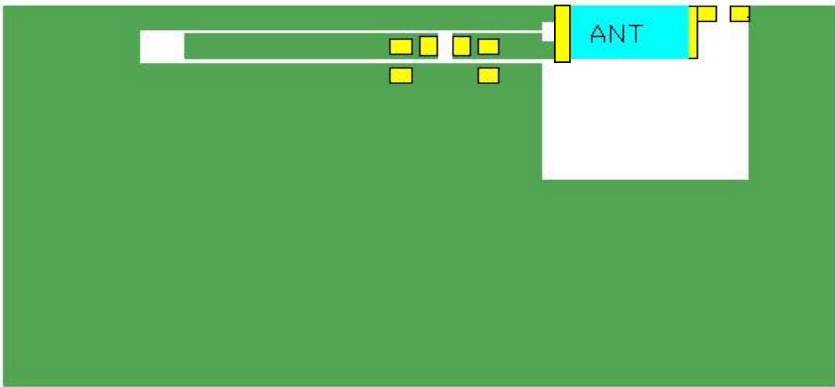


L	W	H	A
3.2±0.2	1.6±0.2	0.52±0.1	0.4±0.1

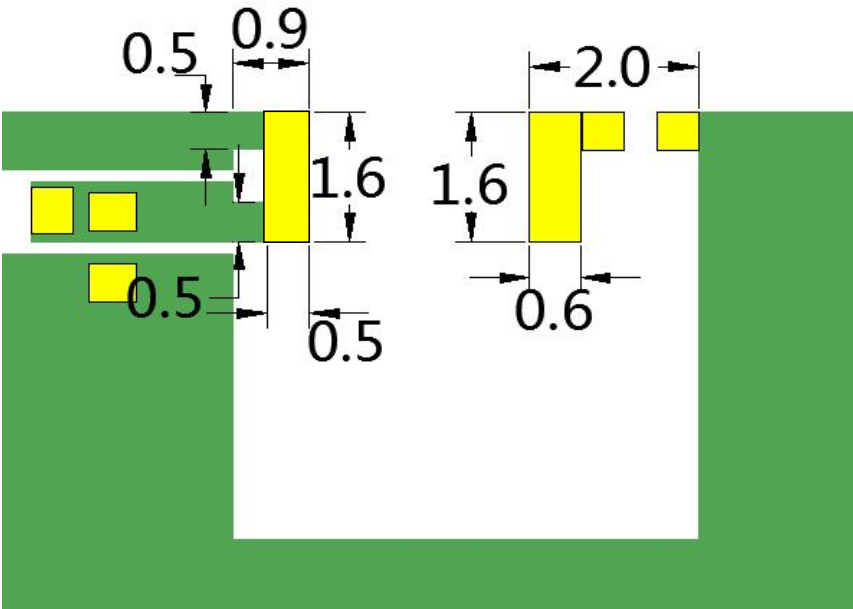
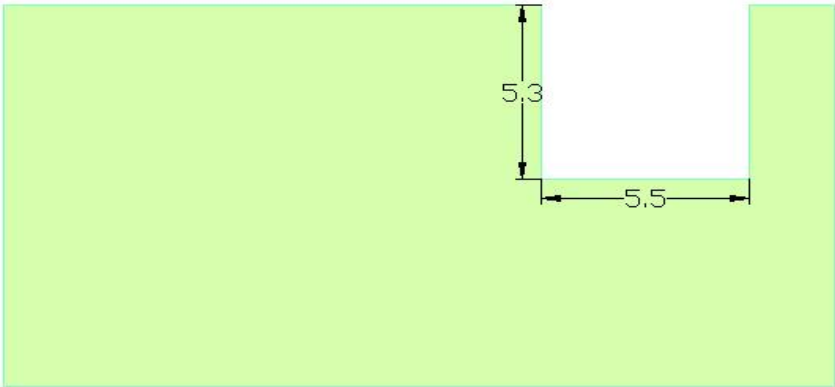
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Test board reference size:

Unit:mm

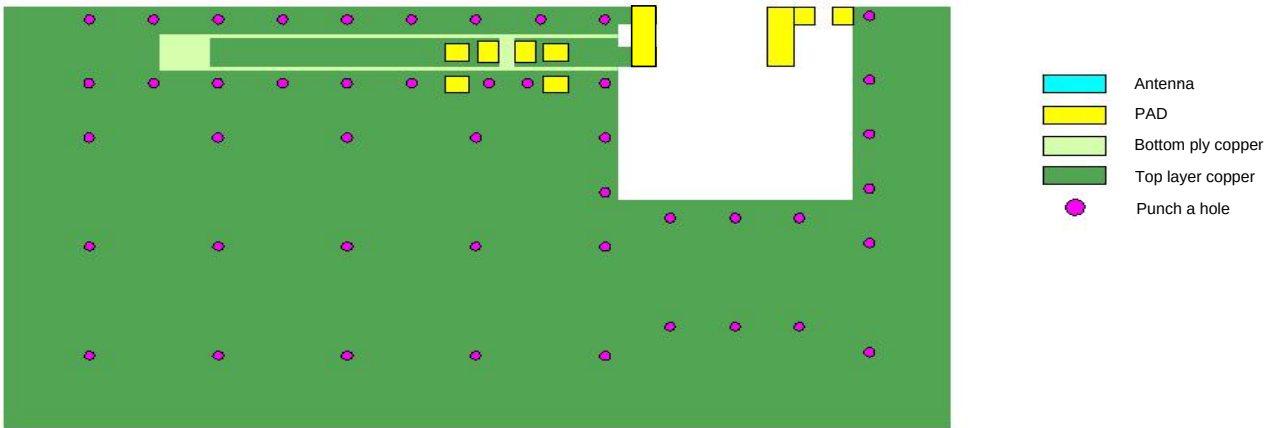


- Antenna
- PAD
- Bottom ply copper
- Top layer copper

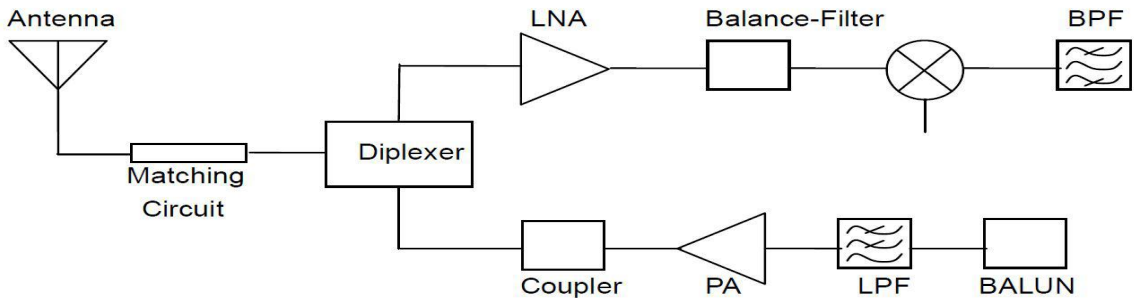


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Reference diagram of punching



APPLICATION GUIDE



5. SPECIFICATIONS:

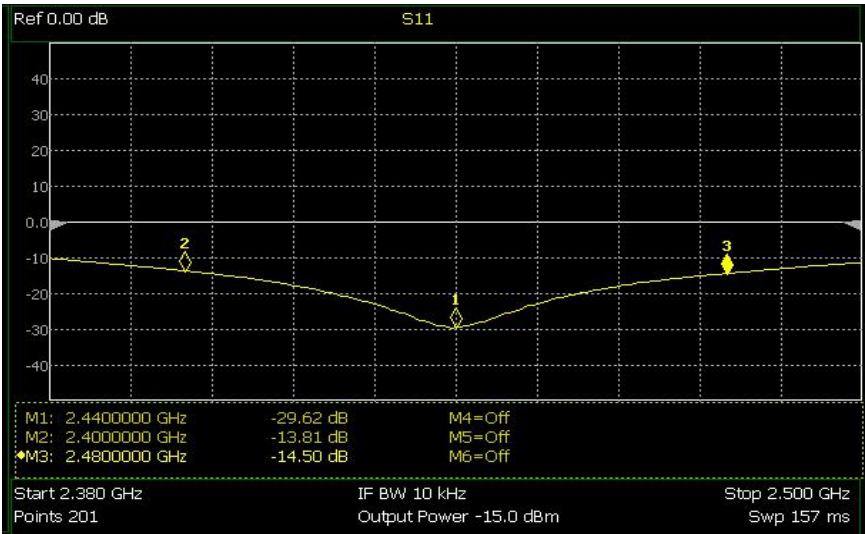
Item of test	Specifications
Bandwidth	2402-2480 MHz
Mode of polarization	Linear polarization
*Maximum gain	2.67dBi
* Efficiency	72.30%
Input impedance	50Ω

Test condition: Test board size 90 40 mm
Matching circuit: Pi matching circuit will be required

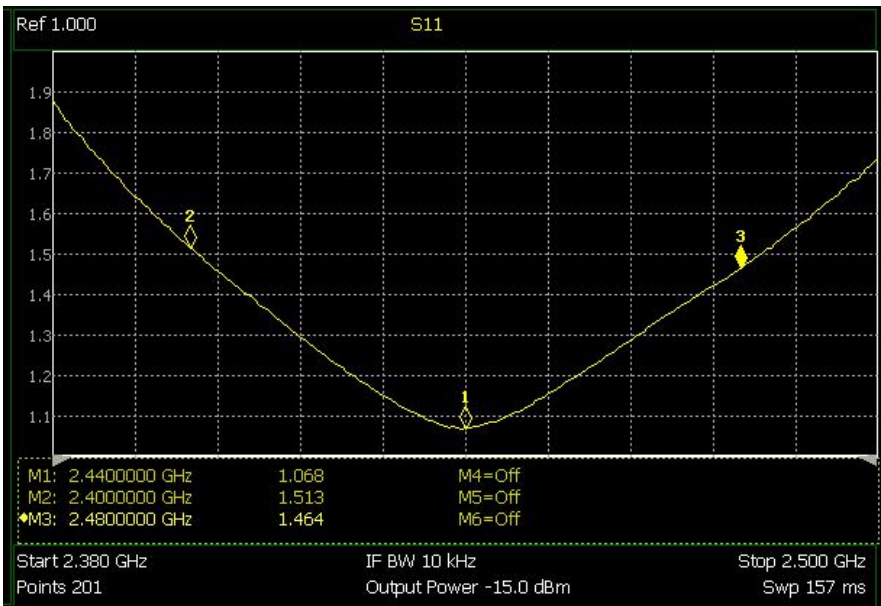
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6. Electrical Characteristics :

Return loss



Standing wave ratio

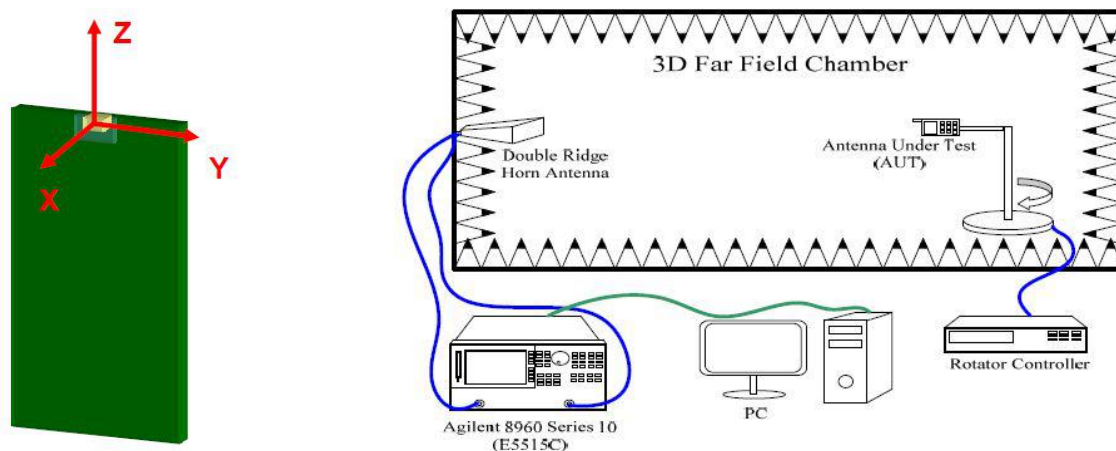


Mark	Frequency	VSWR
1	2400 MHz	1.513
2	2440 MHz	1.068
3	2480 MHz	1.464

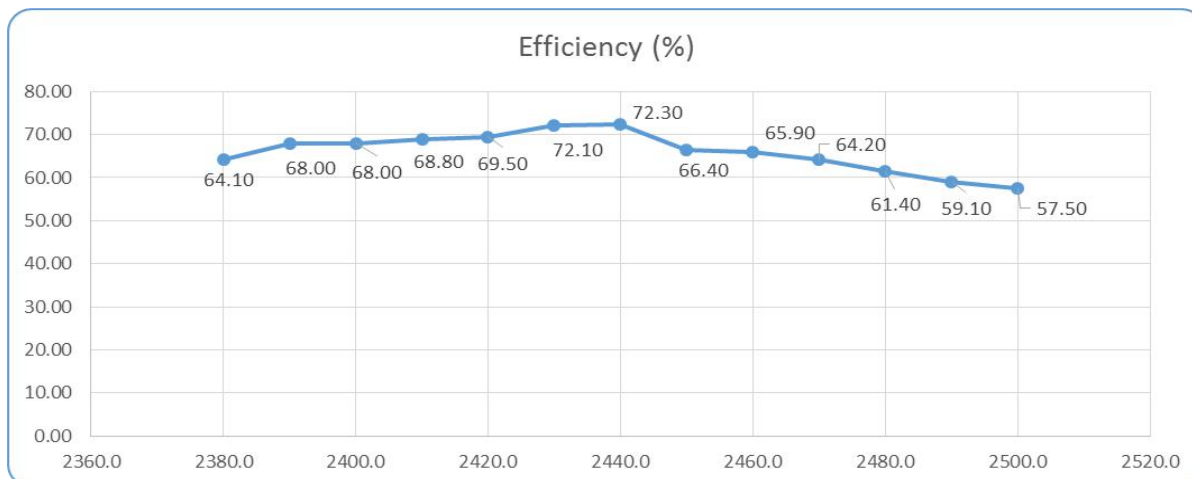
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Radiation Pattern

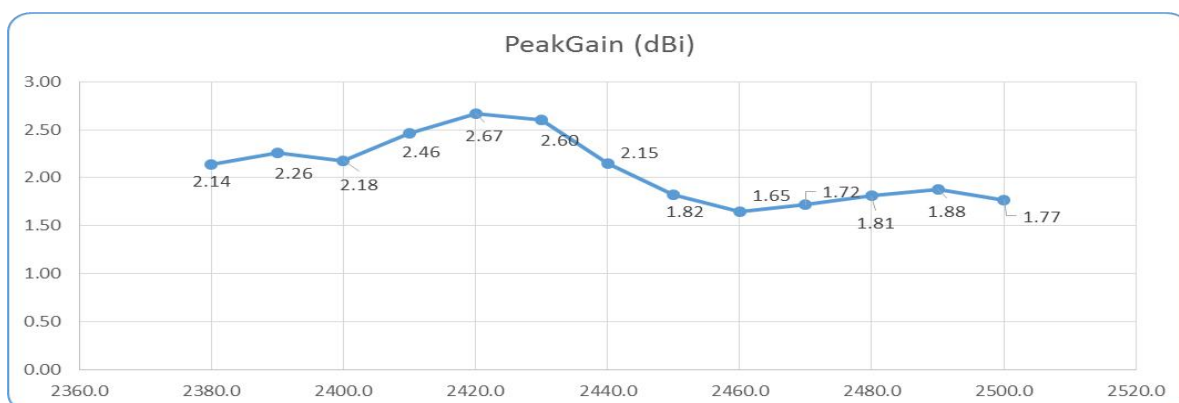
The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.



© Efficiency



Maximum gain



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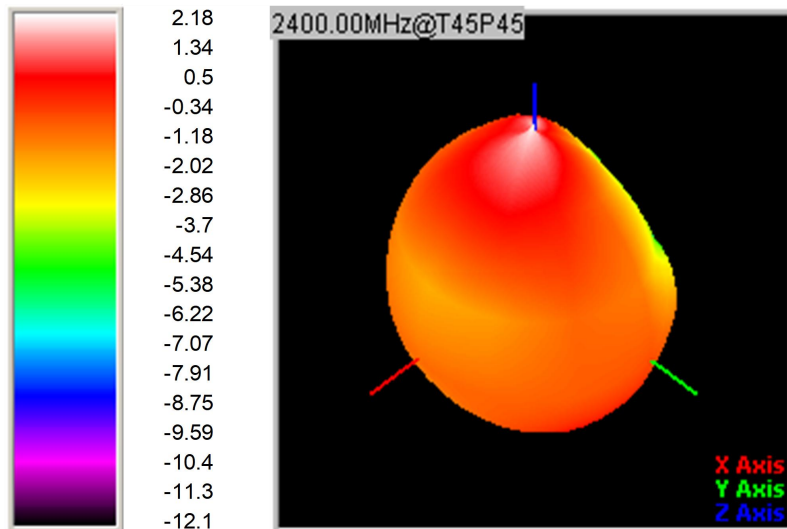
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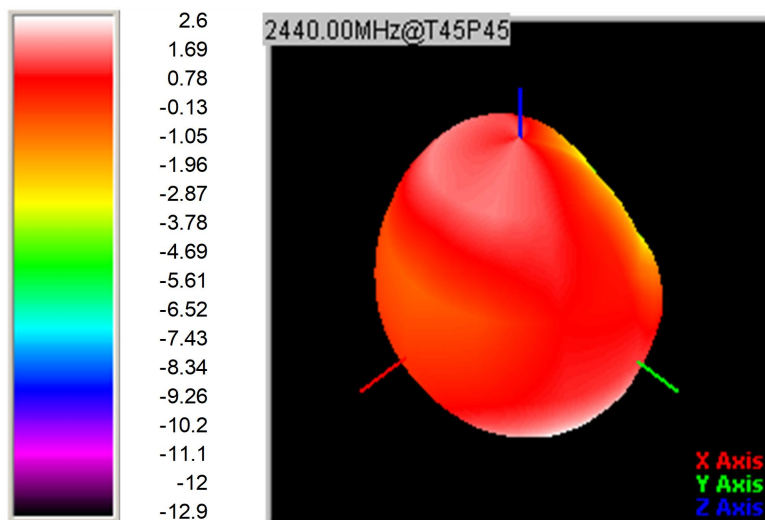
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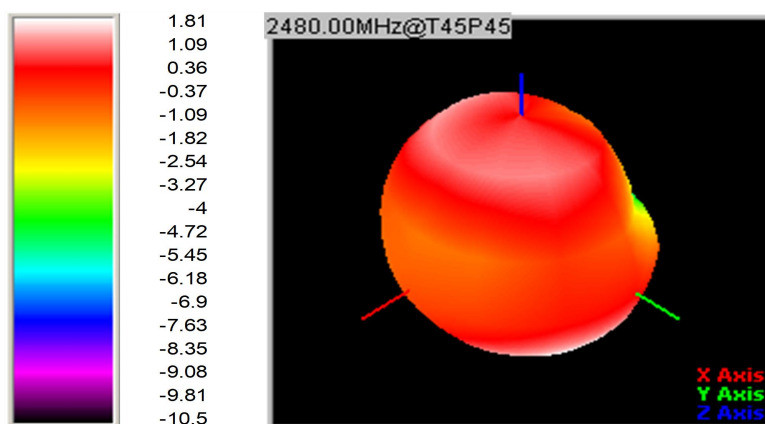
© 3D Gain Pattern (2400 MHz)



© 3D Gain Pattern (2440 MHz)



© 3D Gain Pattern (2480 MHz)



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7. Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at $-40^{\circ}\text{C}\pm 5^{\circ}\text{C}$, 2. Convert to $+105^{\circ}\text{C}$ (5 minutes) 3. 30 ± 3 minutes at $+105^{\circ}\text{C}\pm 5^{\circ}\text{C}$, 4. Convert to -40°C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: $85\pm 5^{\circ}\text{C}$ 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: $150^{\circ}\text{C}\pm 5^{\circ}\text{C}$ 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: $-40^{\circ}\text{C}\pm 5^{\circ}\text{C}$ 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : $260\pm 5^{\circ}\text{C}$ 2. Bathing time: 10 ± 1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245\pm 5^{\circ}\text{C}$ for 3 ± 1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0\sim 30^{\circ}\text{C}$ and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

The temperature should be within $-40\sim 85^{\circ}\text{C}$ and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40°C to $+105^{\circ}\text{C}$.

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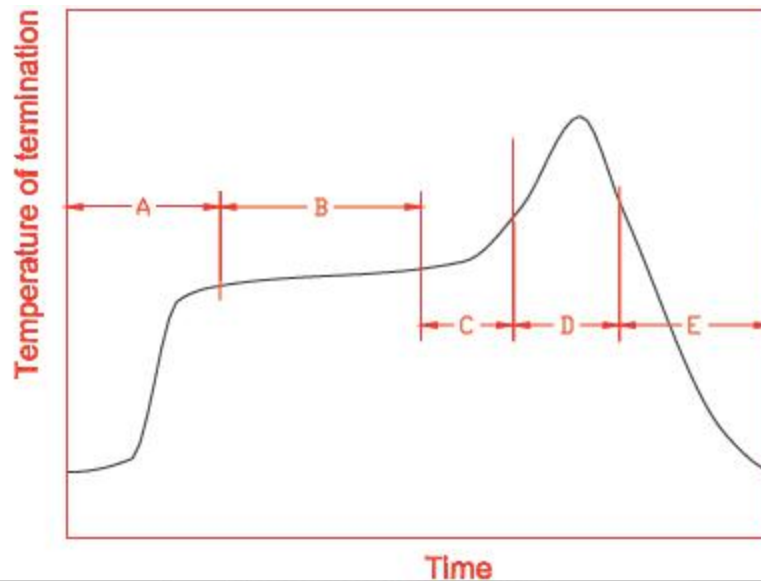
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8. Recommended Reflow Soldering



A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
B	Preheating	140°C to 160°C	60s to 120s
C	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

*reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

- The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

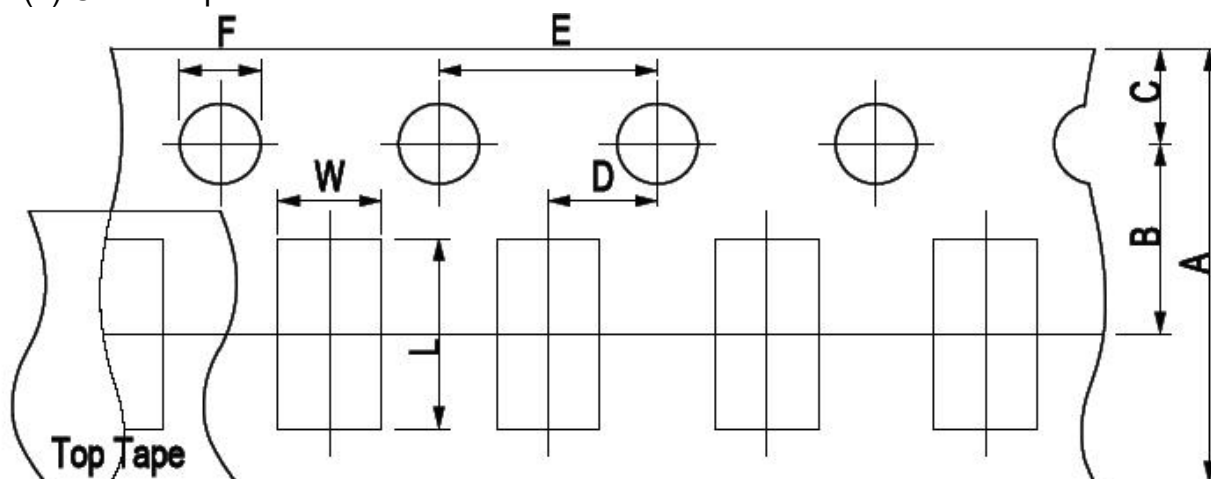
Note that excess of soldering volume will easily get crack the body of this product.

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9. Taping Package and Label Marking: (unit: mm)

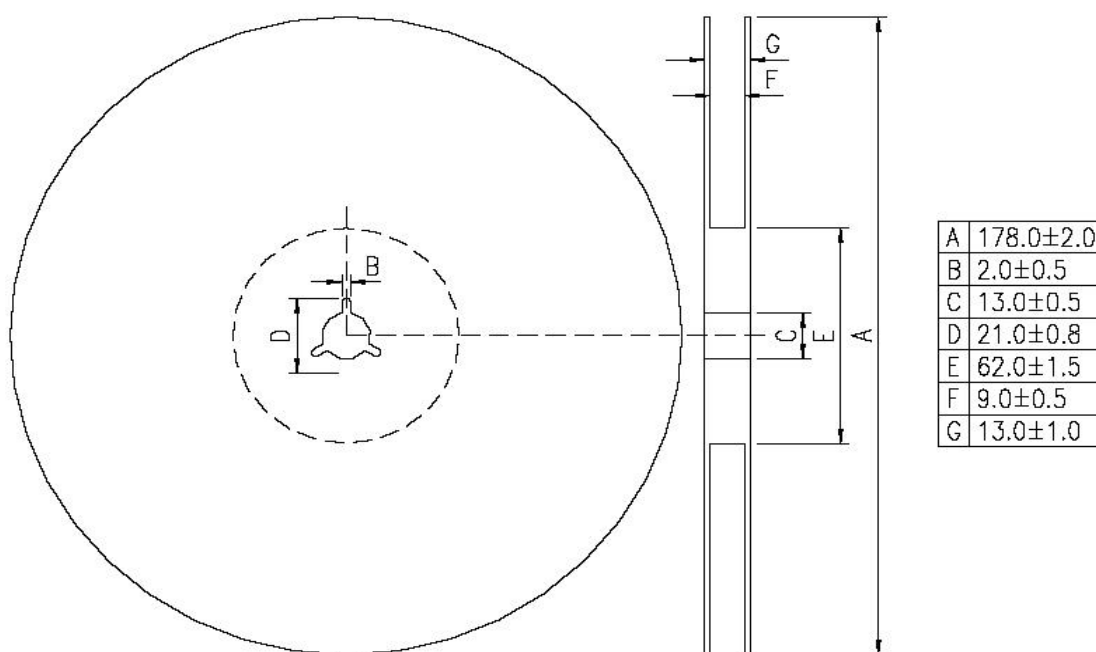
(1) Quantity/Reel: 5000pcs/Reel

(2) Carrier tape dimensions



Type	A	B	C	D	E	F	L	W
2450-21	8.00 ± 0.3	3.50 ± 0.05	1.75 ± 0.1	2.00 ± 0.05	4.00 ± 0.1	1.50 ± 0.1	2.30 ± 0.1	1.55 ± 0.1

(3) Taping reel dimensions



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